# imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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#### **Schottky Rectifier Diode**

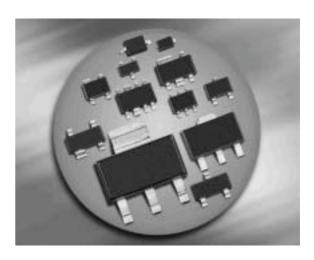
- Reverse voltage: 30 V
- Forward current: 2 A
- Low forward voltage: 0.53 V typ. @ 2 A
- Low leakage current 40 µA typ. @ 30 V
- Low capacitance: 30 pF typ. @ 5 V
- High ESD / transient robustness according to: ESD (HBM): Class 3 B (> 8000 V)
  ESD (MM): Class C ( > 400 V)
  ISO7637-2: Pulse 1 ( -100 V, 2 ms)
  Pulse 2 (-300 V, 50 µs)
  Pulse 3 (-400 V, 100 ns)
- For high efficiency DC/DC conversion, fast switching, polarity protection, rectification and clamping applications
- Very small SMD package (2.0 x 1.25 x 0.9 mm<sup>3</sup>) with improved operating temperature range due to extra-low thermal resistance design (see attached Forward current curves)
- Ideal to replace SMA packages with significant size advantage
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101



#### **BAS3020B**



Туре	Package	Configuration	Marking
BAS3020B	SOT363	single	E9s





Parameter	Symbol	Value	Unit	
Diode reverse voltage <sup>1)</sup>	V <sub>R</sub>	30	V	
Peak reverse voltage <sup>1)</sup>	V <sub>RM</sub>	30		
RMS reverse voltage <sup>1)</sup>	V <sub>R(RMS)</sub>	21		
Forward current <sup>1)2)</sup> , $T_{\rm S} \leq 96^{\circ}{\rm C}$	/ <sub>F</sub>	2	А	
Repetitive peak forward current <sup>2)</sup>	/ <sub>FRM</sub>	3.5		
$(t_{\rm p} \le 1 {\rm ~ms},  D \le 0.5)$				
Non-repetitive peak surge forward current <sup>2)</sup>	/ <sub>FSM</sub>	10		
( <i>t</i> ≤ 10ms)				
Junction temperature	T <sub>i</sub>	150	°C	
Operating temperature range	T <sub>op</sub>	-55125		
Storage temperature	T <sub>stq</sub>	-65150		

Maximum	Ratings	at T <sub>A</sub>	= 25 °C.	unless	otherwise	specified
maximum	Runngo	ωιιд	20 0,	unicoo		opcomea

Т	hermal	Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>3)</sup>	R <sub>thJS</sub>	≤ <b>4</b> 2	K/W

#### **Electrical Characteristics** at $T_{\Lambda}$ = 25°C. unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics		_		_	_
Reverse current <sup>4)</sup>	I <sub>R</sub>				μA
V <sub>R</sub> = 5 V		-	5	25	
<i>V</i> <sub>R</sub> = 10 V		-	10	50	
V <sub>R</sub> = 30 V		-	40	200	
Forward voltage <sup>4)</sup>	V <sub>F</sub>				mV
/ <sub>F</sub> = 500 mA		-	350	410	
<i>I</i> <sub>F</sub> = 1 Α		-	410	470	
I <sub>F</sub> = 2 A		-	530	600	

<sup>1</sup>For  $T_A > 25$  °C the derating of VR and IF has to be considered. Please refer to the attached curves.

<sup>2</sup>Only valid if pins 3 and 4 are connected in parallel.

<sup>3</sup>For calculation of  $R_{\text{thJA}}$  please refer to Application Note Thermal Resistance.

<sup>4</sup>Pulsed test:  $t_p \le 300 \ \mu s$ ;  $D = \le 0.02$ 

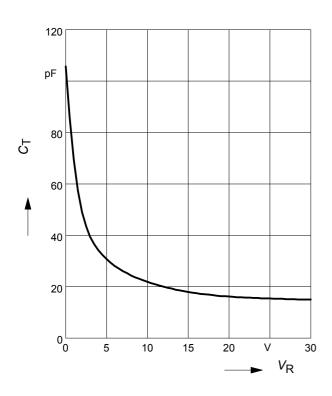


Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics				•	
Diode capacitance	CT				pF
<i>V</i> <sub>R</sub> = 1 V, <i>f</i> = 1 MHz		-	60	70	
V <sub>R</sub> = 5 V, <i>f</i> = 1 MHz		-	30	40	
V <sub>R</sub> = 10 V, <i>f</i> = 1 MHz		-	20	30	



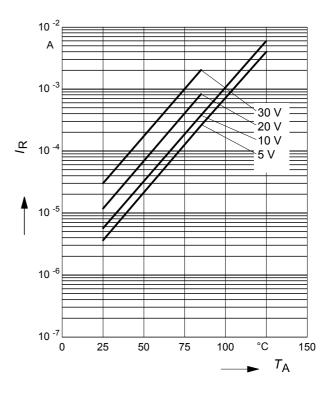
#### **Diode capacitance** $C_T = f(V_R)$

f = 1 MHz



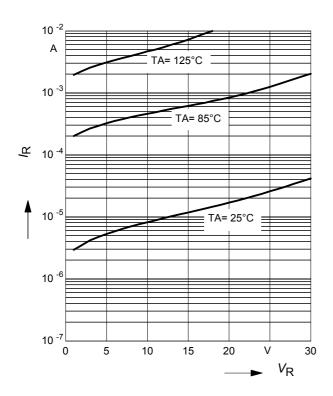
**Reverse current**  $I_{R} = f(T_{A})$ 

 $V_{\rm R}$  = Parameter



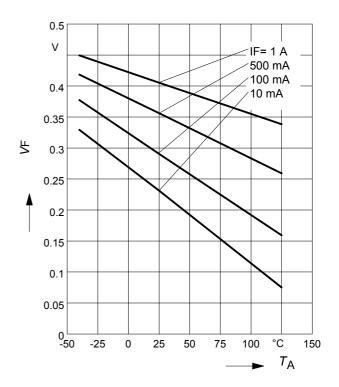
### **Reverse current** $I_{R} = f(V_{R})$

 $T_A$  = Parameter



#### Forward Voltage $V_{\rm F} = f(T_{\rm A})$

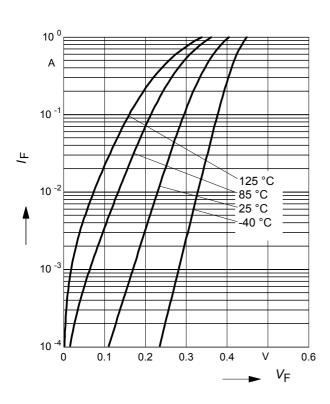
 $I_{\rm F}$  = Parameter





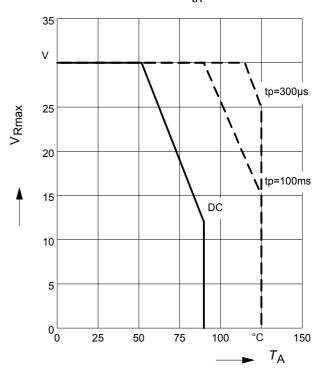
#### Forward current $I_F = f(V_F)$

 $T_A$  = Parameter

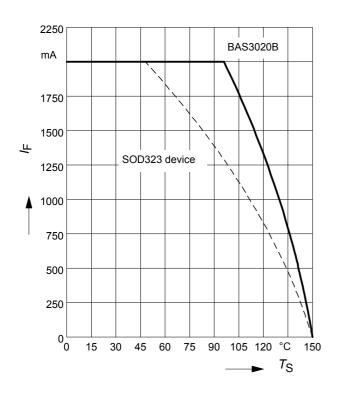


Permissible Reverse voltage  $V_{R} = f(T_{A})$ 

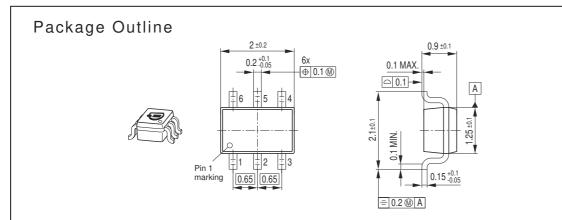
 $t_{\rm p}$  = Parameter, Duty cycle < 0.01 Device mounted on PCB with  $R_{\rm th}$  = 160 k/W



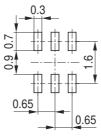
Forward current  $I_{\rm F}$  =  $f(T_{\rm S})$ 





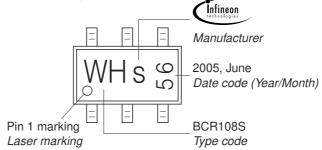


#### Foot Print



#### Marking Layout (Example)

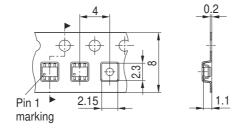
Small variations in positioning of Date code, Type code and Manufacture are possible.



#### Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.





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